

5-103167-3 ✓ ACTIVE

AMPMODU | AMPMODU Headers

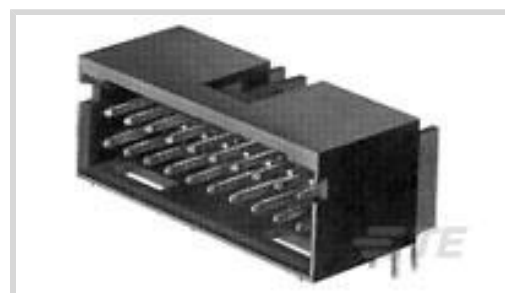
TE Internal #: 5-103167-3

PCB Mount Header, Right Angle, Wire-to-Board, 12 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: **Wire-to-Board**

Number of Positions: **12**

Number of Rows: **2**

Centerline (Pitch): **2.54 mm [.1 in]**

PCB Mount Orientation: **Right Angle**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector System | Wire-to-Board |
| Header Type | Fully Shrouded |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| Number of Positions | 12 |
| Number of Rows | 2 |
| PCB Mount Orientation | Right Angle |

Electrical Characteristics

| | |
|---------------------------------------|-----------------|
| Insulation Resistance | 5000 M Ω |
| Dielectric Withstanding Voltage (Max) | 750 Vrms |

Body Features

| | |
|-----------------------|----------|
| Connector Profile | Standard |
| Primary Product Color | Black |

Contact Features

| | |
|---|---|
| Mating Square Post Dimension | .64 mm[.025 in] |
| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μ m[100 – 200 μ in] |



| | |
|--|-----------------|
| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |

Termination Features

| | |
|---|-----------------------|
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 3.43 mm[.135 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |

Mechanical Attachment

| | |
|-------------------------|---------------|
| Mating Alignment Type | Polarization |
| Mating Retention | With |
| Mating Retention Type | Detent Window |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Alignment | Without |
| PCB Mount Retention | Without |

Housing Features

| | |
|--------------------|----------------|
| Housing Material | Thermoplastic |
| Centerline (Pitch) | 2.54 mm[.1 in] |

Dimensions

| | |
|-----------------------------|-----------------|
| PCB Thickness (Recommended) | 1.4 mm[.055 in] |
| Row-to-Row Spacing | 2.54 mm[.1 in] |

Usage Conditions

| | |
|-----------------------------|----------------------------|
| Housing Temperature Rating | Standard |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |

Operation/Application

| | |
|------------------------|----------------|
| Solder Process Feature | Board Standoff |
| Circuit Application | Signal |



Industry Standards

| | |
|------------------------|-----------------------|
| Agency/Standard | CSA |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |

Packaging Features

| | |
|--------------------|------|
| Packaging Quantity | 208 |
| Packaging Type | Tray |

Product Compliance

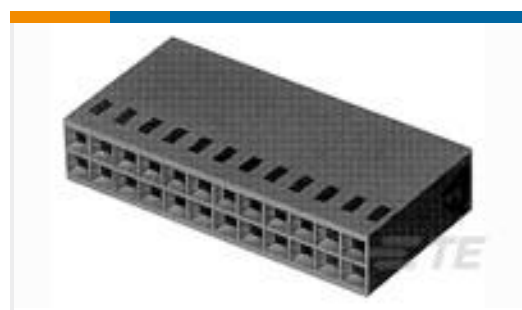
[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC |
| Halogen Content | BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources. |
| Solder Process Capability | Wave solder capable to 240°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 1-86177-3
12 MODIV HSG COMP DR .100CL



TE Part # 87456-7
12 MODIV HSG COMP DR .100CL



TE Part # 3-87977-1
12 MODIV HSG COMP DR .100 POL

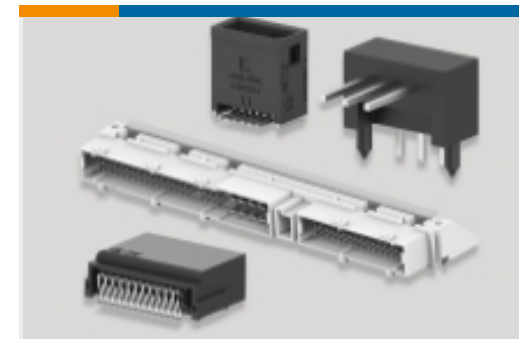
Also in the Series | AMPMODU Headers



PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(6830)



PCB Latches, Locks & Retainers(2)



Wire-to-Board Connector Assemblies
& Housings(5)



Wire-to-Board Connector Contacts(66)

Documents

Product Drawings

12 MODII HDR DRRR SHRD LF

English

CAD Files

Customer View Model

[ENG_CVM_CVM_5-103167-3_R.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_5-103167-3_R.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-103167-3_R.3d_stp.zip](#)

English

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PCB Mount Header, Right Angle, Wire-to-Board, 12 Position, 2.54 mm [.1 in]
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By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION5](#)

English